

| | |
|-----------|--|
| customer | |
| pcb name | |
| WE-number | |
| engineer | |
| date | |



Rigidflex 2F-2Ri

PCB Thickness : 0,97 mm +/- 10% Flex Thickness: 0,19 mm +/- 0,05mm

| Rigid area Structure | Flex area Thickness | Rigid area Thickness | Material description | Flex area Structure | Viatypes | Layer usage | Impedance | |
|----------------------|---------------------|----------------------|-----------------------|---------------------|----------|-------------|-----------|-----------------------|
| | | | | | | | Er | Z[Ohm] / Line / Space |
| Flex Soldermask | 40 | | | | | | | |
| Soldermask | | 15 | | | | | | |
| L1 | 45 | 45 | incl. plating | Top-Layer | | | | |
| | 50 | 50 | Polymide adhesiveless | | | | | |
| L2 | 17 | 17 | | | | | | |
| | 40 | | Coverlay | | | | | |
| | | 90 | FR4 TG150 HF | | | | | |
| | | 610 | FR4 TG150 HF | | | | | |
| L3 | | 17 | | | | | | |
| | | 65 | FR4 TG150 HF | | | | | |
| L4 | | 45 | incl. plating | Bottom-Layer | | | | |
| Soldermask | | 15 | | | | | | |

Notes:

IPC 2223 use A "Flex to install"

Please specify Flex layer as "TOP"

Please regard our sectional design rules 2F-xRi www.we-online.com/3D

Template Revision: 01/2017 by Andreas Schilpp / Michael Kress / Werner Öchslen

| Microvia types - definition of colours | | | Via types - definition of colours | |
|--|----------|--------------------------|-----------------------------------|------------------------------------|
| colour | via type | explanation | Standard Via | Filled & Capped Via (IPC Type VII) |
| | | Microvia standard | | |
| | | Microvia copper filling | | |
| | | Microvia filled & capped | | |